General Description

The HXT8204 VCSEL driver array is a key component for compact, robust, low-power optical transmitter modules. In conjunction with the VCSEL array, the chip handles the complete digital-to-optical conversion, including CML input, laser driver, drive control, and supervision. Standard silicon technology and a small number of additional components allow for cost-effective and compact assemblies.

Applications

- 100G Ethernet SR4 modules
- 100G Ethernet AOC
- InfiniBand EDR transceivers
- InfiniBand EDR active cables
- Proprietary multi-channel optical modules

Features

- Low power consumption of 113mW per channel while delivering 5mA average and 5mA modulation current
- Compatible with common cathode and isolated VCSEL arrays
- 2-wire interface control and symmetric pad design maximize module design flexibility
- Up to 10 mA Average and 10 mA modulation current
- QSFP MSA compliant

Ordering Information

Part	Temp Range	Pin-Package
HXT8204-DNT	0°C to +85°C	Bare Die* 1.950mm x 1.575mm
HXT8204-EVB	Room Temp	Evaluation Board

* Die Design Size; Actual die size may be slightly larger

For price, delivery schedules, and to place orders, please contact IDT: www.IDT.com/go/sales

Device Diagram

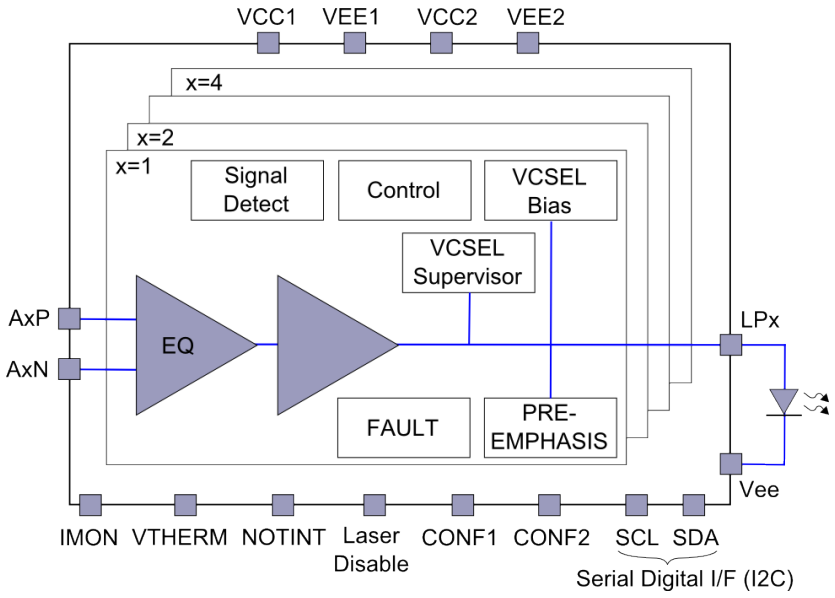

Figure 1: Device diagram

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